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MOSFET – Power, Single, N-Channel

60 V, 4.7 mΩ, 93 A

NTMFS5C646NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	93	Α
Current R _{0JC} (Notes 1, 3)	Steady	T _C = 100°C		65	
Power Dissipation	State	T _C = 25°C	P _D	79	W
R _{θJC} (Note 1)		T _C = 100°C		40	
Continuous Drain		T _A = 25°C	I _D	20	Α
Current R _{0JA} (Notes 1, 2, 3)	Steady	T _A = 100°C	1	14	
Power Dissipation	State	T _A = 25°C	P_{D}	3.7	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C	1	1.8	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \mu s$		I _{DM}	750	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)		I _S	100	Α	
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 5 A)			E _{AS}	185	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C	

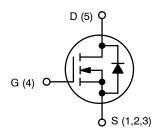
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

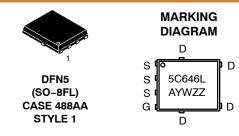
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	1.9	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	41	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	4.7 m Ω @ 10 V	00.4
60 V	6.3 mΩ @ 4.5 V	93 A



N-CHANNEL MOSFET



5C646L = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

NOTE: Some of the device on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				15.5		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25 °C			10	μΑ	
		V _{DS} = 60 V	T _J = 125°C			250		
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{G}$	_S = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 80 \mu A$		1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-4.9		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		3.8	4.7		
		V _{GS} = 4.5 V	I _D = 50 A		5.0	6.3	mΩ	
Forward Transconductance	9 _{FS}	V _{DS} = 15 V, I	_D = 50 A		105		S	
CHARGES, CAPACITANCES & GATE RE	SISTANCE							
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			2164			
Output Capacitance	C _{OSS}				900		pF	
Reverse Transfer Capacitance	C _{RSS}				17			
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V}; I_D = 25 \text{ A}$ $V_{GS} = 10 \text{ V}, V_{DS} = 30 \text{ V}; I_D = 25 \text{ A}$			15.7			
Total Gate Charge	Q _{G(TOT)}				33.7			
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 25 A			1.5		nC	
Gate-to-Source Charge	Q _{GS}				5.6		1	
Gate-to-Drain Charge	Q_{GD}				5.1			
Plateau Voltage	V_{GP}				2.8		V	
SWITCHING CHARACTERISTICS (Note	5)							
Turn-On Delay Time	t _{d(ON)}				10.4			
Rise Time	t _r	V _{GS} = 4.5 V, V _Γ	_{DS} = 30 V,		14.9]	
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V},$ $I_{D} = 25 \text{ A}, R_{G} = 2.5 \Omega$			23.6		ns -	
Fall Time	t _f				5.1			
DRAIN-SOURCE DIODE CHARACTERIS	STICS							
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.88	1.2	.,,	
		I _S = 50 A	T _J = 125°C		0.78		-	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$			40.9			
Charge Time	t _a				20.8		ns	
Discharge Time	t _b				20.1			
Reverse Recovery Charge	Q _{RR}				32		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

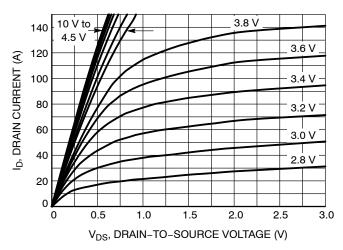


Figure 1. On-Region Characteristics

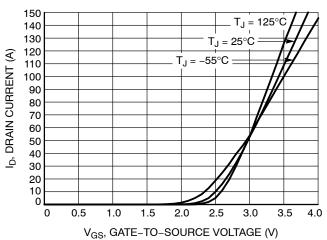


Figure 2. Transfer Characteristics

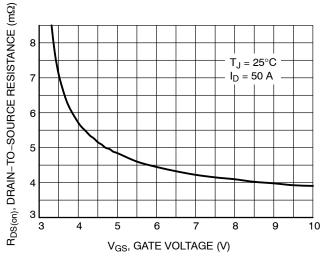


Figure 3. On-Resistance vs. Gate-to-Source Voltage

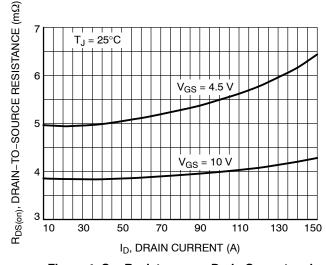


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

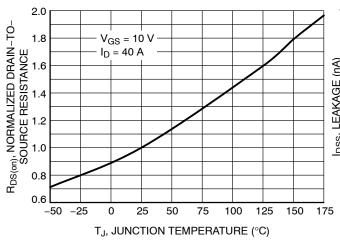


Figure 5. On–Resistance Variation with Temperature

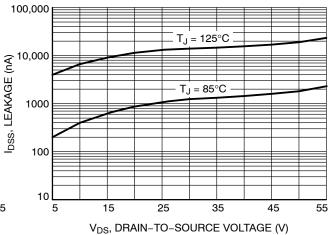
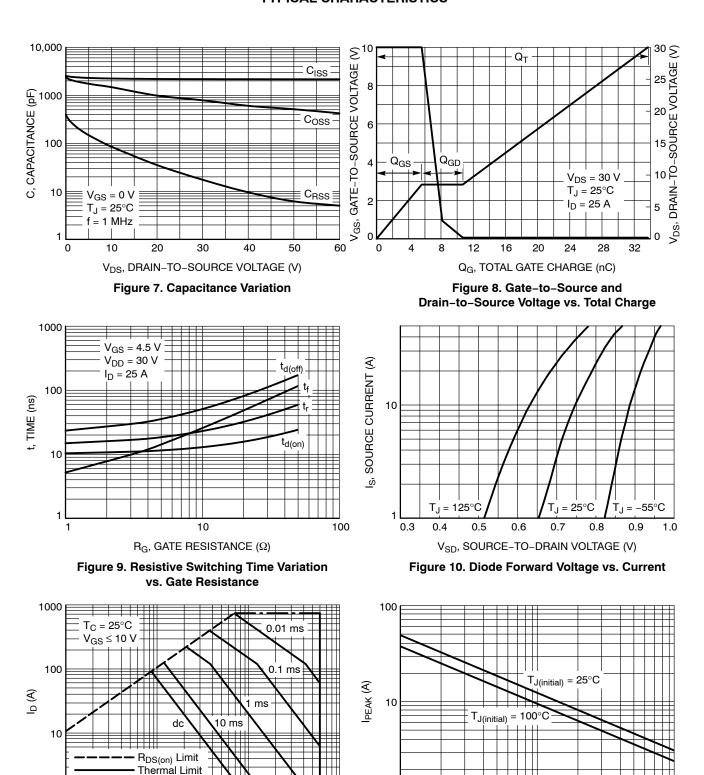


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



 $V_{DS}\left(V\right)$ Figure 11. Safe Operating Area

10

Package Limit

0.1

TIME IN AVALANCHE (s) Figure 12. I_{PEAK} vs. Time in Avalanche

1E-03

1E-02

100

1E-04

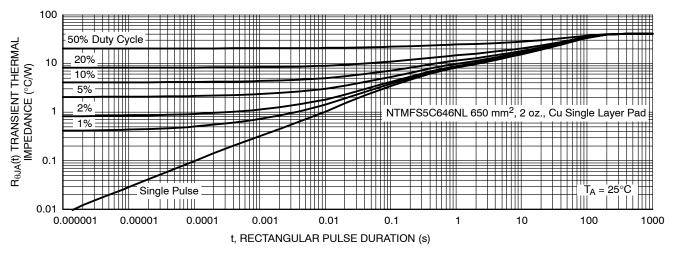


Figure 13. Thermal Response

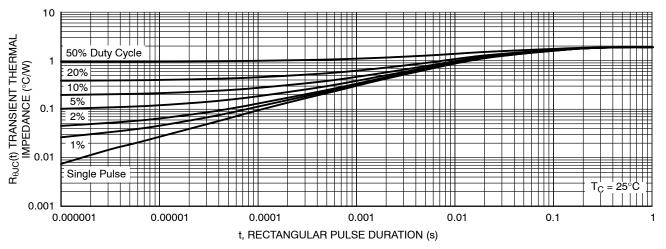


Figure 14. Thermal Response

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C646NLT1G	5C646L	DFN5 (Pb-Free)	1500 / Tape & Reel
DISCONTINUED (Note 6)			
NTMES5C646NLT3G	506451	DEN5	1500 / Tane & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

(Pb-Free)

^{6.} **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.





DFN5 5x6, 1.27P (SO-8FL) CASE 488AA **ISSUE N**

DATE 25 JUN 2018

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location Α

= Lot Traceability

Υ = Year W = Work Week

ZZ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

SIDE VIEW

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)		PAGE 1 OF 1	

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